

(Designation of Document)

ABSTRACT

(Abstract)

(Problem) The present invention is to provide a polishing apparatus and method which can easily correct irregularities of a polishing action, and polish a workpiece with an intensive polishing action on a desired localized area thereof.

(Means for Resolution) A polishing apparatus having a turntable 5 with an upper surface to which a polishing cloth 6 is attached and a top ring 1, for polishing a semiconductor wafer 4 to a flat mirror finish by placing the semiconductor wafer 4 between the turntable 5 and the top ring 1 and pressing the semiconductor wafer 4 under a given pressure, characterized in that: a plurality of openings are provided in a holding surface, for holding the semiconductor wafer 4, of the top ring 1 for ejecting pressurized fluid, the plurality of openings are divided into a plurality of areas, and the pressurized fluid is capable of being supplied to each of the areas.

(Selected Figure)

Fig. 1